

SEP 05 2007

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 10/620,468  
Confirmation No. .... 8630  
Filing Date ..... July 15, 2003  
Inventor ..... Dinesh Chopra et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2822  
Examiner ..... Tran, Thanh Y.  
Attorney's Docket No. .... MI22-2345  
Title: Conductive Connection Forming Methods, Oxidation Reducing Methods,  
and Integrated Circuits Formed Thereby

**TERMINAL DISCLAIMER**

I, James E. Lake, residing at Liberty Lake, Washington, represent that I am the attorney of record for Micron Technology, Inc., a corporation of the state of Delaware. Micron Technology, Inc. is the owner of all right, title and interest of this U.S. Patent Application Serial No. 10/620,468, filed July 15, 2003, as evidenced by an assignment recorded July 31, 2000, Reel 010965, Frames 0422-0426 in the U.S. Patent and Trademark Office.

Micron Technology, Inc. is also the owner of all rights, title and interest in U.S. Patent No. 6,613,671, as evidenced by an assignment recorded July 31, 2000, at Reel 010965, Frames 0422-0426, in the U.S. Patent and Trademark Office.

The evidentiary documents have been reviewed, and I certify that, to the best of assignee's knowledge and belief, title is in the assignee seeking to take this action.

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Micron Technology, Inc. hereby disclaims the terminal part of any future patent granted on this U.S. Patent Application Serial No. 10/620,468 which extends beyond the expiration date of U.S. Patent No. 6,613,671, and further hereby agrees that any future patent so granted on this U.S. Patent Application Serial No. 10/620,468 shall be enforceable only for and during such period that the legal title on the U.S. Patent No. 6,613,671 shall be the same as the legal title to any patent issued from U.S. Patent Application Serial No. 10/620,468. This agreement is to run with any patent granted on the application and is to be binding upon the grantee of such patent and its successors or assigns.

Micron Technology, Inc. does not disclaim any terminal part of any patent granted on this 10/620,468 application prior to the expiration date of the full statutory term of the United States Patent No. 6,613,671 in the event that it later: expires for failure to pay a maintenance fee, is held unenforceable, is found invalid by a court of competent jurisdiction, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. §1.321(a), has all claims canceled by a reexamination certificate, is reissued in any manner or is otherwise terminated prior to expiration of its full statutory term as presently shortened by any terminal disclaimer, except for the separation of legal title stated above.


The fee required by 37 C.F.R. 1.20(d) is submitted herewith. The Commissioner is hereby authorized to charge payment of any additional fees or credit overpayments to Deposit Account No. 23-0925.

The undersigned, James E. Lake, hereby indicates that he is authorized to sign this document on behalf of the assignee, Micron Technology, Inc.

Respectfully submitted,

Dated: 05 Sep 2007

By: \_\_\_\_\_

  
James E. Lake  
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